



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



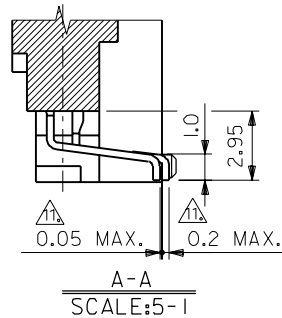
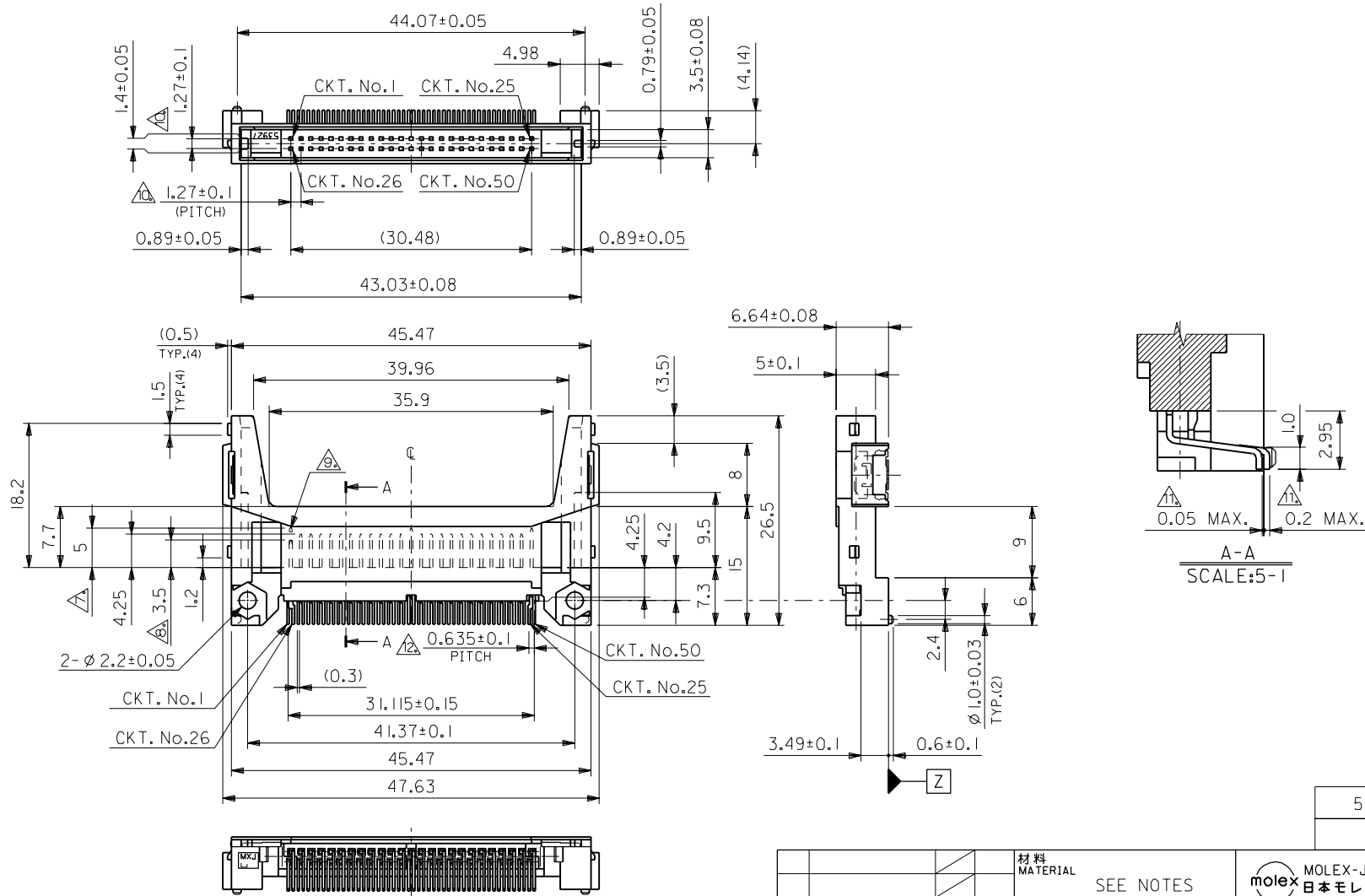
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





53927-5010
ENG. No.

角 度 ANGLE		±3°				材 料 MATERIAL	SEE NOTES
30 以上 OVER		+0.3				仕 上 げ FINISH	SEE NOTES
10 以上 30 未 満 OVER UNDER		+0.25				適 用 電 線 範 圍 WIRE RANGE	— #
10 未 満 UNDER		+0.2				被 覆 外 徑 INS. RANGE	— #
一 般 公 差 GENERAL TOLERANCES			記 号 LTR	変 更 内 容 REVISION RECORD	DR. DATE	DRAPP'D BY	CHK'D BY
			0	新 規 作 成 (LD70244)	16/08/20	J. Hanaya	M. Saitoh
						尺 度 SCALE	2 - 1

53927-5010		ENG. No.	
MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社			
REVISE ONLY ON CAD SYSTEM			
TITLE 名称			
CFA CARD CONN. 50P HEADER ASS'Y (REVERSE TYPE)			
DWG. NO.	SHEET 1 OF 2	REV	
SD-53927-5010		0	

DWG. NO. SD-53927-5010

注)
NOTES 1. 材質

MATERIAL

ハウジング : ガラス入りLCP UL94V-0
HOUSING: LCP G.F. UL94V-0
ピン : リン青銅
PIN: PHOSPHOR BRONZE
ネール : リン青銅
NAIL: PHOSPHOR BRONZE

2. メッキ仕様
PLATING

PIN 接点部 : パラジウムニッケル下地、金メッキ
CONTACT AREA: Au OVER Pd-Ni
半田付け部 : 半田メッキ
SOLDER TAIL AREA: TIN-LEAD
下地メッキ : ニッケルメッキ
UNDERPLATING: Ni OVER ALL

NAIL 半田メッキ

Sn-Pb
下地メッキ : 銅メッキ
UNDERPLATING: Cu OVER ALL

3. 推奨基板厚 : t0.8 MIN.
RECOMMENDED P.C.B. THICKNESS: t0.8 MIN.

4. 適合カード厚
RECOMMENDED CARD THICKNESS

接続部 : 3.3±0.1
CONNECTING AREA: 3.3±0.1

5. 適合カード幅 : 42.8±0.1
RECOMMENDED CARD WIDTH: 42.8±0.1

6. ハウジング色 : 白
HOUSING COLOR: WHITE

△7 寸法適用極 : 1,13,38,50
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS
1,13,38 AND 50.

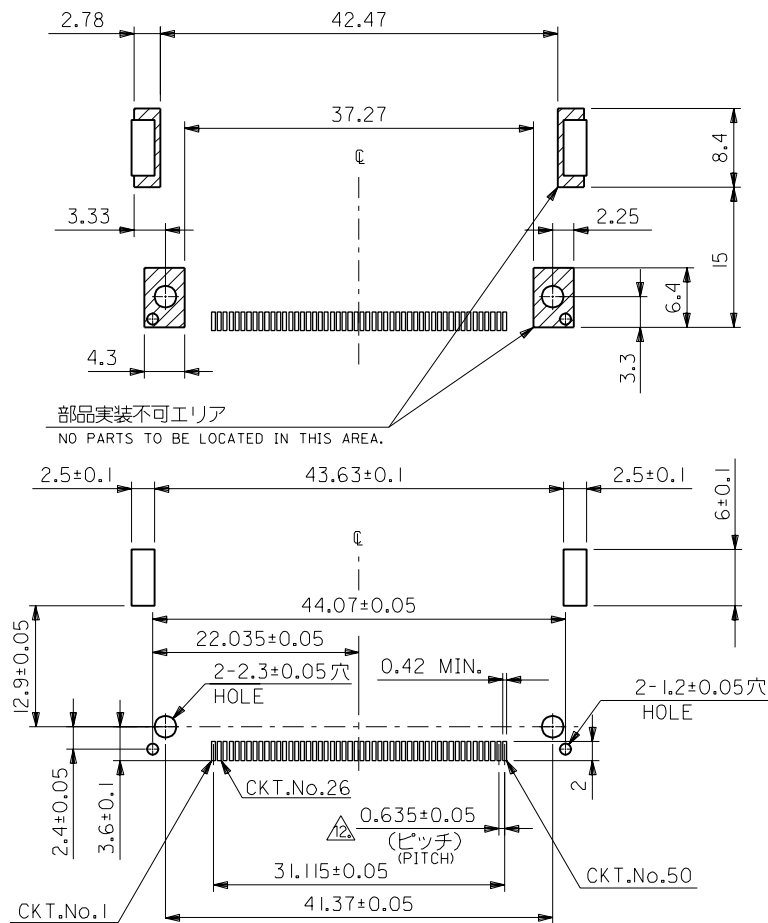
△8 寸法適用極 : 25,26
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.

△9 ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。
PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1
WHEN MEASURED FROM PIN BASE.

△10 ピン根元に適用する。
THIS DIMENSION TO BE MEASURED AT PIN BASE.

△11 ソルダータールは、Z面を基準とし上へ0.05下へ0.2の範囲にあり、
且つソルダータールの平坦度は、0.15 MAX.とし、テール先端にて測定する。
SOLDERTAILS TO BE WITHIN 0.05 UPWARD AND
0.2 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF
SOLDERTAILS TO BE WITHIN 0.15.
MEASUREMENT POINT IS SOLDERTAILS TIP.

△12 公差非累積
NON-CUMULATIVE



基板推奨寸法
RECOMMENDED P.C.B. LAYOUT

角 度 ANGLE		±3°			材 料 MATERIAL	—	MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
30以上 OVER		+0.3			仕 上 げ FINISH	—	
10以上 30未滿 UNDER		+0.25			適 用 電 線 範 圍 WIRE RANGE	—	TITLE 名称
10未滿 UNDER		+0.2			被 覆 外 徑 INS. RANGE	—	CFA CARD CONN. 50P HEADER ASS'Y (REVERSE TYPE)
一 般 公 差 GENERAL TOLERANCES			記 号 LTR	変 更 内 容 REVISION RECORD	DR. DATE	CHK'D BY	DWG. NO. SHEET 2 OF 2 REV
			0	SEE SHEET 1 OF 2	16/08/20	M. Saito	SD-53927-5010 0
					尺 度 SCALE	2 - 1	